

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): H. MAEJIMA ET AL.

Serial No. : Not Assigned Yet
(Reissue of Patent No.: 5,230,747
Issued: July 27, 1993)

Filed: November 3, 2000

For: WAFER HAVING CHAMFERED BEND PORTIONS IN THE
JOINT REGIONS BETWEEN THE CONTOUR OF THE WAFER
AND THE CUT-AWAY PORTION OF THE WAFER

CLAIM FOR PRIORITY

Assistant Commissioner of Patents
Washington, D.C. 20231

November 3, 2000

Sir:

Under the provisions of 35 U.S.C. and 37 CFR 1.55, the
applicant(s) hereby claim the right of priority based on:

Japan 570131949, filed July 30, 1982

The certified copy of said Japanese application was filed
in parent Patent No. 5,230,747, issued July 27, 1993.

Respectfully submitted,

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